



## Ceramic transient voltage suppressors

### SMD multilayer transient voltage suppressors, high-speed series

Series/Type:

Date: November 2012

Multilayer varistors (MLVs)

High-speed series

SMD

EPCOS type designation system for high-speed series

CA	04	P2	S	14	T	HS	G
<p>Construction:            CT Single chip with nickel barrier termination (AgNiSn)            CA Chip array with nickel barrier termination (AgNiSn)</p>							
<p>Case sizes:            0201 0201 single chip            0402 0402 single chip            0603 0603 single chip            05 0508 array            06 0612 array</p>							
<p>Number of elements per component:            Single chip            P4 Array with 4 elements</p>							
<p>Tolerance of the varistor voltage:            L ±15%            S Special tolerance            V Special tolerance</p>							
<p>Maximum RMS operating voltage (<math>V_{RMS}</math>):            14 14 V            Typical varistor voltage (<math>V_{\sigma}</math>):            150 150 V</p>							
Internal coding							
High-speed series							
<p>Taping mode:            G 180-mm reel</p>							

## Multilayer varistors (MLVs)

### High-speed series

#### SMD

#### Features

- ESD protection level acc. to ISO 10605, IEC 61000-4-2 level 4
- Bidirectional protection
- Capacitance ratings down to 2 pF
- Low insertion loss
- Low leakage current
- No signal distortion
- RoHS-compatible
- Suitable for lead-free soldering

#### Applications

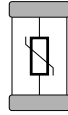
- ESD protection for high-speed data lines such as USB 2.0, firewire, etc.
- ESD protection for I/O ports of video and audio lines
- Integrated solutions for connectors in mobile communication and handheld devices

#### Design

- Multilayer technology
- Lack of plastic or epoxy encapsulation for flammability rating better than UL 94 V-0
- Termination (see "Soldering directions"): CT and CA types with nickel barrier terminations (AgNiSn), recommended for lead-free soldering, and compatible with tin/lead solder.

#### Single chip

#### Internal circuit



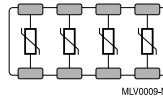
MLV0006-H

#### Available case sizes:

EIA	Metric
0201	0603
0402	1005
0603	1608

#### Array

#### Internal circuit



MLV0009-M

#### 4-fold array

#### Available case sizes:

EIA	Metric	Version
0508	1220	4-fold array
0612	1632	4-fold array

## Multilayer varistors (MLVs)

### High-speed series

### SMD

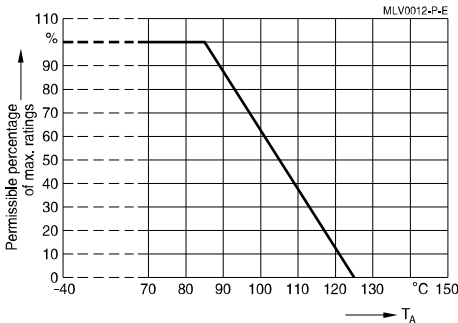
#### General technical data

Maximum RMS operating voltage		$V_{RMS,max}$	4 ... 25	V
Maximum DC operating voltage		$V_{DC,max}$	5.5 ... 32	V
Contact discharge ESD capability	to IEC 61000-4-2	$V_{ESD,contact}$	8	kV
Air discharge ESD capability	to IEC 61000-4-2	$V_{ESD,air}$	15	kV
Maximum surge current	(8/20 $\mu$ s)	$I_{surge,max}$	1 ... 5	A
Typical capacitance	(1 MHz, 1 V)	$C_{typ}$	2 ... 15	pF
Maximum clamping voltage	(8/20 $\mu$ s)	$V_{clamp,max}$	59 ... 350	V
Operating temperature	for 0201, 0402 and arrays	$T_{op}$	40/+85	$^{\circ}$ C
Operating temperature	for 0603	$T_{op}$	55/+125	$^{\circ}$ C
Storage temperature	for 0201, 0402 and arrays	LCT/UCT	40/+125	$^{\circ}$ C
Storage temperature	for 0603	LCT/UCT	55/+150	$^{\circ}$ C

#### Temperature derating

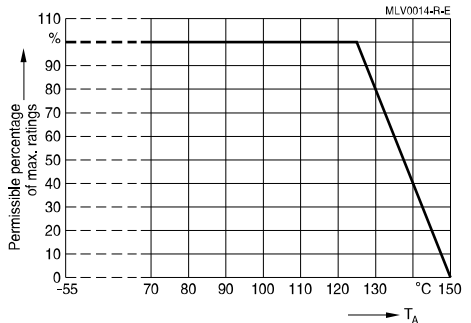
##### Climatic category:

40/+85  $^{\circ}$ C for chip size 0201, 0402  
and arrays



##### Climatic category:

55/+125  $^{\circ}$ C for chip size 0603



**Multilayer varistors (MLVs)**
**High-speed series**
**SMD**
**Electrical specifications and ordering codes**
**Maximum ratings (T<sub>op,max</sub>)**

Type	Ordering code	V <sub>RMS,max</sub> V	V <sub>DC,max</sub> V	I <sub>surge,max</sub> (8/20 μs) A	W <sub>max</sub> (ESD) <sup>1)</sup> mJ	T <sub>op,max</sub> °C
<b>4-fold array</b>						
CA05P4S14THSG	B72714A8140S160	14	16	2	30	+85
CA06P4V150THSG	B72724A8151V062	14	16	1	30	+85
<b>Single chip</b>						
CT0201S4AHSG	B72440T8040S160	4	5.5	-	-	+85
CT0402S14AHSG	B72590T8140S160	14	16	2	30	+85
CT0402V150HSG	B72590T8151V060	14	16	1	30	+85
CT0603S14AHSG	B72500T8140S160	14	16	5	30	+125
CT0603L25HSG	B72500T8250L060	25	32	5	50	+125

**Characteristics (T<sub>A</sub> = 25 °C)**

Type	V <sub>V,min</sub> (1 mA) V	V <sub>V,max</sub> (1 mA) V	V <sub>clamp,max</sub> V	I <sub>clamp</sub> (8/20 μs) A	C <sub>typ</sub> (1 MHz, 1 V) pF	C <sub>max</sub> (1 MHz, 1 V) pF
<b>4-fold array</b>						
CA05P4S14THSG	24	32	59	1	10	15
CA06P4V150THSG	-	175	350	1	3	5
<b>Single chip</b>						
CT0201S4AHSG	21	39	70	1	-	10
CT0402S14AHSG	23	33	66	1	10	15
CT0402V150HSG	-	200	290	1	2	3
CT0603S14AHSG	23	33	66	1	15	30
CT0603L25HSG	51.9	70.1	120	1	10	15

1) To IEC 61000-4-2, level 4

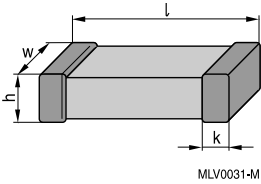
## Multilayer varistors (MLVs)

### High-speed series

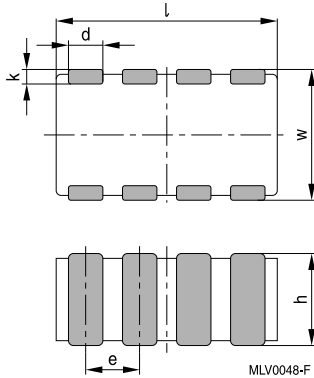
### SMD

#### Dimensional drawings

##### Single chip



##### 4-fold array



#### Dimensions in mm

Case size EIA / mm	l	w	h	d	e	k
0201 / 0603	0.60 ±0.03	0.30 ±0.03	0.33 max.	-	-	0.15 ±0.05
0402 / 1005	1.00 ±0.15	0.50 ±0.10	0.6 max.	-	-	0.10 ... 0.30
0508 / 1220	2.00 ±0.20	1.25 ±0.20	0.9 max.	0.30 ±0.10	0.50 ±0.10	0.20 +0.2/ 0.1
0603 / 1608	1.60 ±0.15	0.80 ±0.10	0.9 max.	-	-	0.10 ... 0.40
0612 / 1632	3.20 ±0.20	1.60 ±0.15	0.9 max.	0.40 ±0.15	0.80 ±0.15	0.20 ±0.10

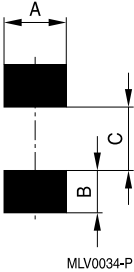
## Multilayer varistors (MLVs)

### High-speed series

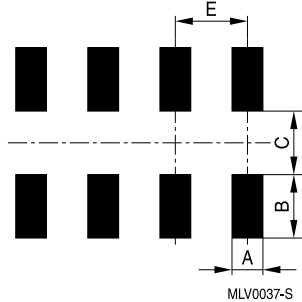
### SMD

#### Recommended solder pad layout

##### Single chip



##### 4-fold array



#### Dimensions in mm

Case size EIA / mm		A	B	C	E
0201 / 0603	Single chip	0.30	0.25	0.30	-
0402 / 1005	Single chip	0.60	0.60	0.50	-
0603 / 1608	Single chip	1.00	1.00	1.00	-
0508 / 1220	4-fold array	0.35	0.90	0.40	0.50
0612 / 1632	4-fold array	0.50	0.70	1.20	0.76

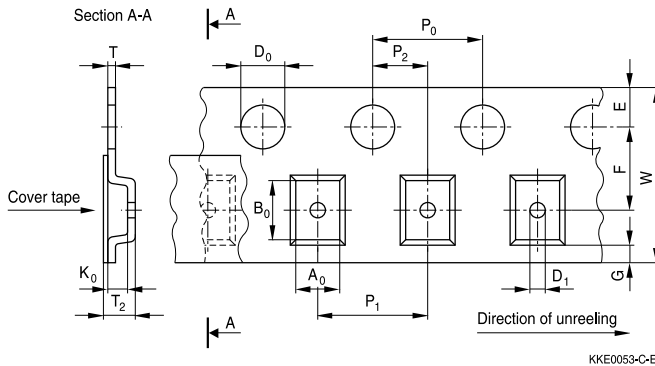
#### Delivery mode

EIA case size	Taping	Reel size mm	Packing unit pcs.	Type	Ordering code
<b>4-fold array</b>					
0508	Cardboard	180	4000	CA05P4S14THSG	B72714A8140S160
0612	Blister	180	3000	CA06P4V150THSG	B72724A8151V062
<b>Single chip</b>					
0201	Cardboard	180	15000	CT0201S4AHSG	B72440T8040S160
0402	Cardboard	180	10000	CT0402S14AHSG	B72590T8140S160
0402	Cardboard	180	10000	CT0402V150HSG	B72590T8151V060
0603	Cardboard	180	4000	CT0603L25HSG	B72500T8250L060
0603	Cardboard	180	4000	CT0603S14AHSG	B72500T8140S160

Taping and packing

1 Taping and packing for SMD components

1.1 Blister tape (the taping to IEC 60286-3)



KKE0053-C-E

Dimensions in mm

	8-mm tape					12-mm tape		16-mm tape		Tolerance
	Case size (inch/mm)					Case size (inch/mm)		Case size (inch/mm)		
			0508/ 1220	0612/ 1632	1012/ 2532					
	0603/ 1608	0506/ 1216	0805/ 2012	1206/ 3216	1210/ 3225	1812/ 4532	2220/ 5750	3225	4032	
A <sub>0</sub>	0.9 ±0.10	1.50	1.60	1.90	2.80	3.50	5.10	7.00	8.60	±0.20
B <sub>0</sub>	1.75 ±0.10	1.80	2.40	3.50	3.50	4.80	6.00	8.70	10.60	±0.20
K <sub>0</sub>	1.0	0.80	1.80			2.60		5.00		max.
T	0.30					0.30		0.30		max.
T <sub>2</sub>	1.3	1.20	2.50			3.50		5.50		max.
D <sub>0</sub>	1.50					1.50		1.50		+0.10/ 0
D <sub>1</sub>	1.00					1.50		1.50		min.
P <sub>0</sub>	4.00					4.00		4.00		±0.10 <sup>1)</sup>
P <sub>2</sub>	2.00					2.00		2.00		±0.05
P <sub>1</sub>	4.00					8.00		12.00		±0.10
W	8.00					12.00		16.00		±0.30
E	1.75					1.75		1.75		±0.10
F	3.50					5.50		7.50		±0.05
G	0.75					0.75		0.75		min.

1) E±0.2 mm over 10 sprocket holes.



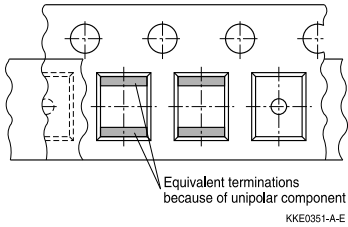
## Multilayer varistors (MLVs)

### High-speed series

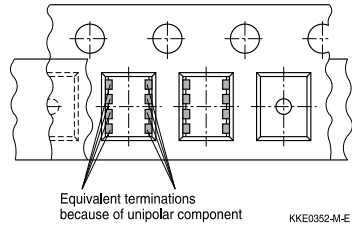
### SMD

#### Part orientation in tape pocket for blister tape

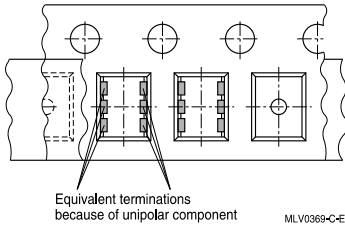
For discrete chip, case sizes 0603, 0805, 1206, 1210, 1812 and 2220



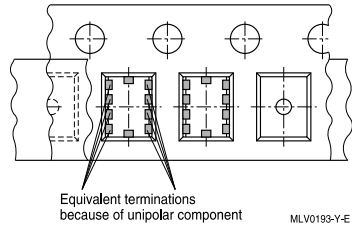
For array, case sizes 0612



For arrays 0506 and 1012



For filter array, case size 0508



#### Additional taping information

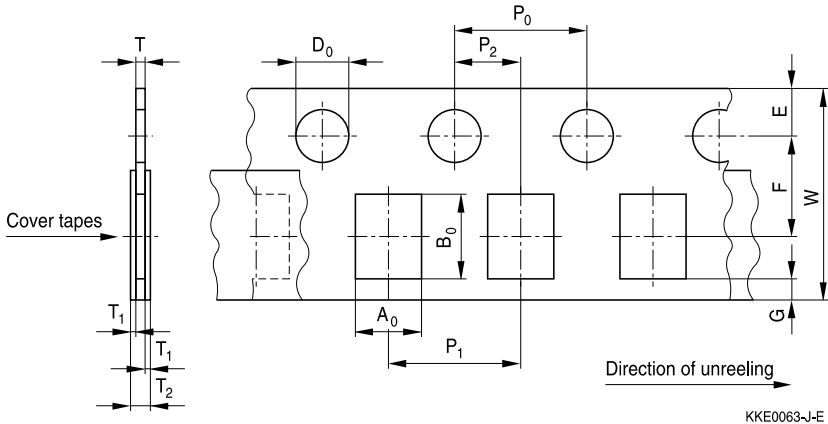
Reel material	Polystyrol (PS)
Tape material	Polystyrol (PS) or Polycarbonat (PC) or PVC
Tape break force	min. 10 N
Top cover tape strength	min. 10 N
Top cover tape peel force	0.2 to 0.6 N for 8-mm tape and 0.2 to 0.8 N for 12-mm tape at a peel speed of 300 mm/min
Tape peel angle	Angle between top cover tape and the direction of feed during peel off: 165° to 180°
Cavity play	Each part rests in the cavity so that the angle between the part and cavity center line is no more than 20°

Multilayer varistors (MLVs)

High-speed series

**SMD**

1.2 Cardboard tape (taping to IEC 60286-3)



KKE0063-J-E

Dimensions in mm

	8-mm tape						Tolerance
	Case size (inch/mm)					Case size (inch/mm)	
	0201/0603	0402/1005	0405/1012	0603/1608	1003/2508	0508/1220	
A <sub>0</sub>	0.38 ±0.05	0.60	1.05	0.95	1.00	1.60	±0.20
B <sub>0</sub>	0.68 ±0.05	1.15	1.60	1.80	2.85	2.40	±0.20
T	0.35 ±0.02	0.60	0.75	0.95	1.00	0.95	max.
T <sub>2</sub>	0.4 min.	0.70	0.90	1.10	1.10	1.12	max.
D <sub>0</sub>	1.50 ±0.1	1.50				1.50	+0.10/ 0
P <sub>0</sub>	4.00						±0.10 <sup>2)</sup>
P <sub>2</sub>	2.00						±0.05
P <sub>1</sub>	2.00 ±0.05	2.00	4.00	4.00	4.00	4.00	±0.10
W	8.00						±0.30
E	1.75						±0.10
F	3.50						±0.05
G	1.35	0.75					min.

2) £0.2 mm over 10 sprocket holes.

## Multilayer varistors (MLVs)

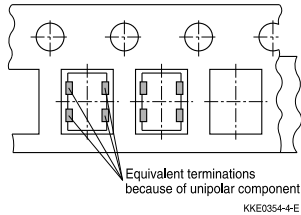
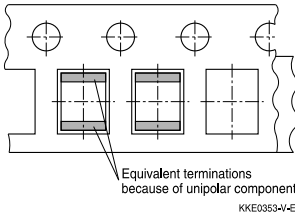
### High-speed series

### SMD

#### Part orientation in tape pocket for cardboard tape

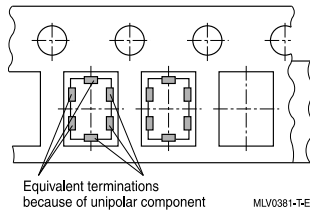
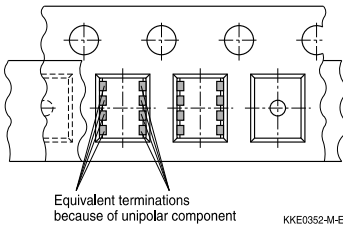
For discrete chip case sizes 0201, 0402, 0603 and 1003

For array case size 0405



For array case size 0508

For filter array, case size 0405

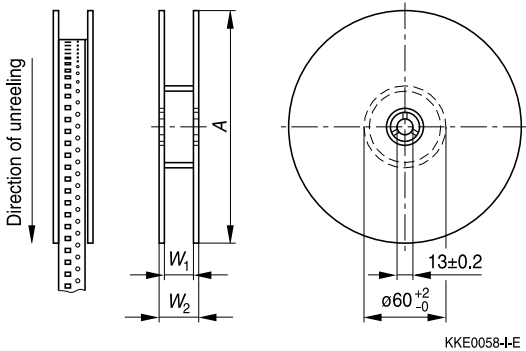


#### Additional taping information

Reel material	Polystyrol (PS)
Tape material	Cardboard
Tape break force	min. 10 N
Top cover tape strength	min. 10 N
Top cover tape peel force	0.1 to 0.65 N at a peel speed of 300 mm/min
Tape peel angle	Angle between top cover tape and the direction of feed during peel off: 165° to 180°
Cavity play	Each part rests in the cavity so that the angle between the part and cavity center line is no more than 20°

**SMD**

1.3 Reel packing

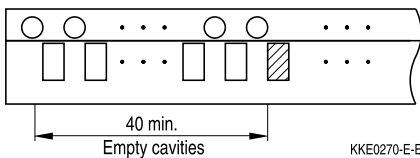


Dimensions in mm

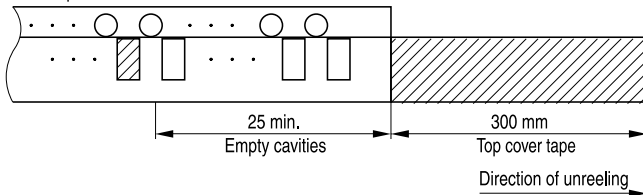
	8-mm tape		12-mm tape		16-mm tape
	180-mm reel	330-mm reel	180-mm reel	330-mm reel	330-mm reel
A	180 3/+0	330 2.0	180 3/+0	330 2.0	330 2.0
W <sub>1</sub>	8.4 +1.5/ 0	8.4 +1.5/ 0	12.4 +1.5/ 0	12.4 +1.5/ 0	16.4 +1.5/ 0
W <sub>2</sub>	14.4 max.	14.4 max.	18.4 max.	18.4 max.	22.4 max.

Leader, trailer

Tape end (Trailer)



Leader part



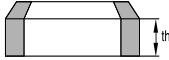
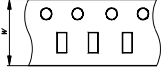
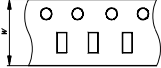

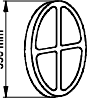
KKE0289-Q-E

Multilayer varistors (MLVs)

High-speed series

**SMD**

1.4 Packing units for discrete chip and array chip

Case size inch/mm	 Chip thickness th	 Cardboard tape W	 Blister tape W	 Æ 180-mm reel pcs.	 Æ 330-mm reel pcs.
0201/0603	0.33 mm	8 mm		15000	
0402/1005	0.6 mm	8 mm		10000	
0405/1012	0.7 mm	8 mm		5000	
0506/1216	0.5 mm		8 mm	4000	
0508/1220	0.9 mm	8 mm	8 mm	4000	
0603/1608	0.9 mm	8 mm	8 mm	4000	16000
0612/1632	0.9 mm		8 mm	3000	
0805/2012	0.7 mm		8 mm	3000	12000
	0.9 mm		8 mm	3000	
	1.3 mm		8 mm	3000	
1003/2508	0.9 mm	8 mm		4000	
1012/2532	1.0 mm		8 mm	2000	
1206/3216	0.9 mm		8 mm	3000	
	1.3 mm		8 mm	3000	
	1.4 mm		8 mm	2000	
	1.6 mm		8 mm	2000	
1210/3225	0.9 mm		8 mm	3000	
	1.3 mm		8 mm	3000	
	1.4 mm		8 mm	2000	
	1.6 mm		8 mm	2000	
1812/4532	1.3 mm		12 mm	1500	4000 3000
	1.4 mm		12 mm	1000	
	1.6 mm		12 mm		
	2.3 mm		12 mm		
2220/5750	1.3 mm		12 mm	1500	3000 3000
	1.4 mm		12 mm	1000	
	2.0 mm		12 mm		
	2.3 mm		12 mm		
3225	3.2 mm		16 mm		1000
	4.5 mm		16 mm		1000
4032	3.2 mm		16 mm		1000
	4.5 mm		16 mm		1000

Multilayer varistors (MLVs)

High-speed series

SMD

2 Delivery mode for leaded SHCV varistors

Standard delivery mode for SHCV types is bulk. Alternative taping modes (AMMO pack or taped on reel) are available upon request.

Packing units for:

Type	Pieces
SR6	2000
SR1 / SR2	1000

For types not listed in this data book please contact EPCOS.

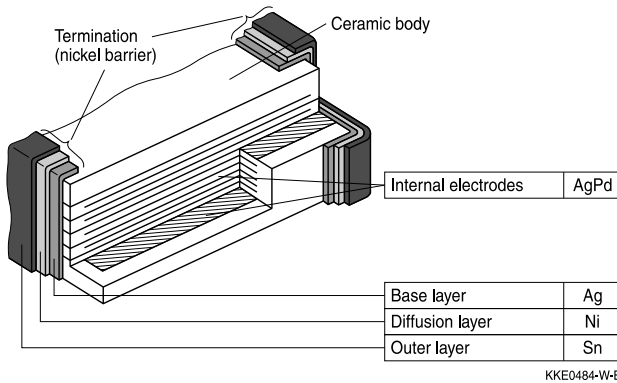
SMD

Soldering directions

1 Terminations

1.1 Nickel barrier termination

The nickel barrier layer of the silver/nickel/tin termination prevents leaching of the silver base metallization layer. This allows great flexibility in the selection of soldering parameters. The tin prevents the nickel layer from oxidizing and thus ensures better wetting by the solder. The nickel barrier termination is suitable for all commonly-used soldering methods.

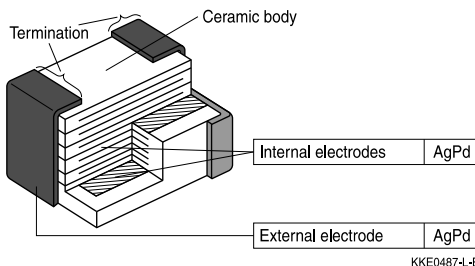


Multilayer CTVS: Structure of nickel barrier termination

1.2 Silver-palladium termination

Silver-palladium terminations are used for the large case sizes 1812 and 2220 and for chips intended for conductive adhesion. This metallization improves the resistance of large chips to thermal shock.

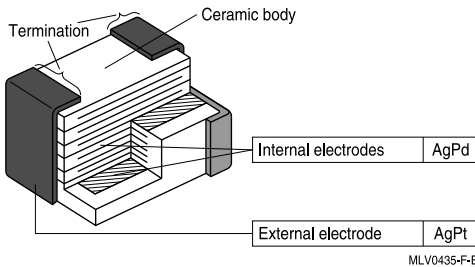
In case of conductive adhesion, the silver-palladium metallization reduces susceptibility to corrosion. Silver-palladium termination can be used for smaller case sizes (only chip) for hybrid applications as well. The silver-palladium termination is not approved for lead-free soldering.



Multilayer varistor: Structure of silver-palladium termination

### 1.3 Silver-platinum termination

Silver-platinum terminations are mainly used for the large case sizes 1812 and 2220. The silver-platinum termination is approved for reflow soldering, SnPb soldering and lead-free soldering with a silver containing solder paste. In case of SnPb soldering, a solder paste Sn62Pb36Ag2 is recommended. For lead-free reflow soldering, a solder paste SAC, e.g. Sn95.5Ag3.8Cu0.7, is recommended.

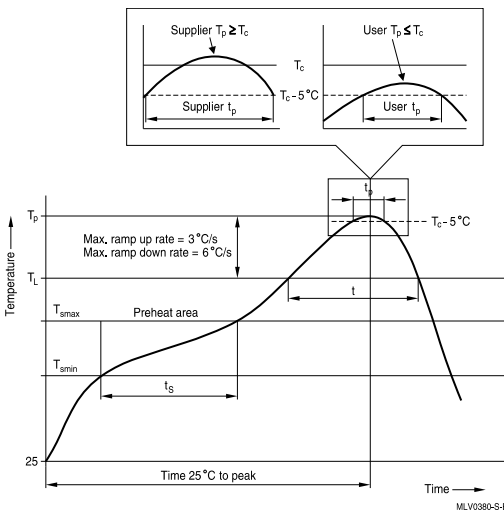


Multilayer varistor: Structure of silver-platinum termination

## 2 Recommended soldering temperature profiles

### 2.1 Reflow soldering temperature profile

Recommended temperature characteristic for reflow soldering following JEDEC J-STD-020D





## Multilayer varistors (MLVs)

### High-speed series

### SMD

Profile feature		Sn-Pb eutectic assembly	Pb-free assembly
Preheat and soak			
- Temperature min	$T_{smin}$	100 °C	150 °C
- Temperature max	$T_{smax}$	150 °C	200 °C
- Time	$t_{smin}$ to $t_{smax}$	60 ... 120 s	60 ... 180 s
Average ramp-up rate	$T_{smax}$ to $T_p$	3 °C/ s max.	3 °C/ s max.
Liquidous temperature	$T_L$	183 °C	217 °C
Time at liquidous	$t_L$	60 ... 150 s	60 ... 150 s
Peak package body temperature	$T_p$ <sup>1)</sup>	220 °C ... 235 °C <sup>2)</sup>	245 °C ... 260 °C <sup>2)</sup>
Time ( $t_p$ ) <sup>3)</sup> within 5 °C of specified classification temperature ( $T_c$ )		20 s <sup>3)</sup>	30 s <sup>3)</sup>
Average ramp-down rate	$T_p$ to $T_{smax}$	6 °C/ s max.	6 °C/ s max.
Time 25 °C to peak temperature		maximum 6 min	maximum 8 min

1) Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

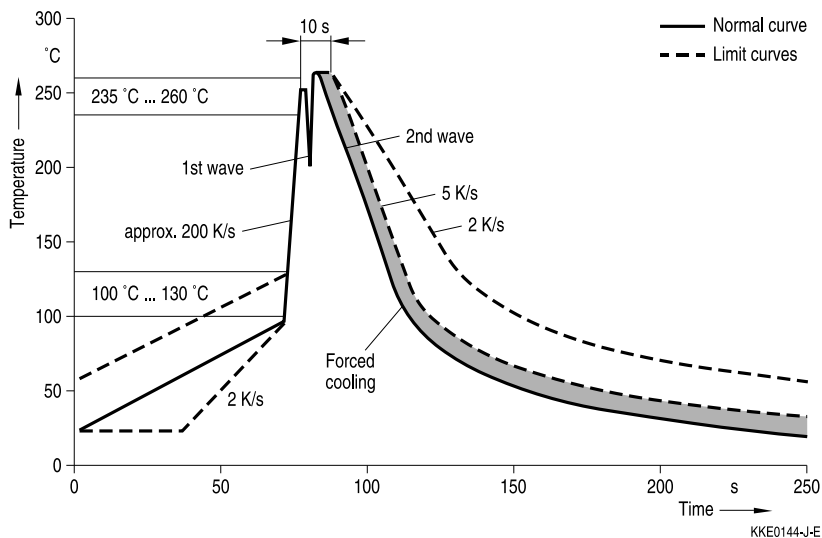
2) Depending on package thickness. For details please refer to JEDEC J-STD-020D.

3) Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.

Note: All temperatures refer to topside of the package, measured on the package body surface.  
Number of reflow cycles: 3

## 2.2 Wave soldering temperature profile

Temperature characteristics at component terminal with dual-wave soldering



**Multilayer varistors (MLVs)**
**High-speed series**
**SMD**
**2.3 Lead-free soldering processes**

EPCOS multilayer CTVS with AgNiSn termination are designed for the requirements of lead-free soldering processes only.

Soldering temperature profiles to JEDEC J-STD-020D, IEC 60068-2-58 and ZVEI recommendations.

**3 Recommended soldering methods - type-specific releases by EPCOS**
**3.1 Overview**

Type	Case size	Reflow soldering		Wave soldering	
		SnPb	Lead-free	SnPb	Lead-free
CT... / CD...	0201/ 0402	Approved	Approved	No	No
CT... / CD...	0603 ... 2220	Approved	Approved	Approved	Approved
CN...	0603 ... 2220	Approved	No	Approved	No
CN...K2	1812, 2220	Approved	Approved	No	No
Arrays	0405 ... 1012	Approved	Approved	No	No
ESD/EMI filters	0405, 0508	Approved	Approved	No	No
CU	3225, 4032	Approved	Approved	Approved	Approved
SHCV	-	No	No	Approved	Approved

**3.2 Nickel barrier and AgPt terminated multilayer CTVS**

All EPCOS MLVs with nickel barrier and AgPt termination are suitable and fully qualified for lead-free soldering. The nickel barrier layer is 100% matte tin-plated.

**3.3 Silver-palladium terminated MLVs**

AgPd-terminated MLVs are mainly designed for conductive adhesion technology on hybrid material. Additionally MLVs with AgPd termination are suitable for reflow and wave soldering with SnPb solder.

Note:

Lead-free soldering is not approved for MLVs with AgPd termination.

**3.4 Silver-platinum terminated MLVs**

The silver-platinum termination is approved for reflow soldering, SnPb soldering and lead-free with a silver containing solder paste. In case of SnPb soldering, a solder paste Sn62Pb36Ag2 is recommended. For lead-free reflow soldering, a solder paste SAC, e.g. Sn95.5Ag3.8Cu0.7, is recommended.

SMD

3.5 Tinned copper alloy

All EPCOS CU types with tinned termination are approved for lead-free and SnPb soldering.

3.6 Tinned iron wire

All EPCOS SHCV types with tinned termination are approved for lead-free and SnPb soldering.

4 Solder joint profiles / solder quantity

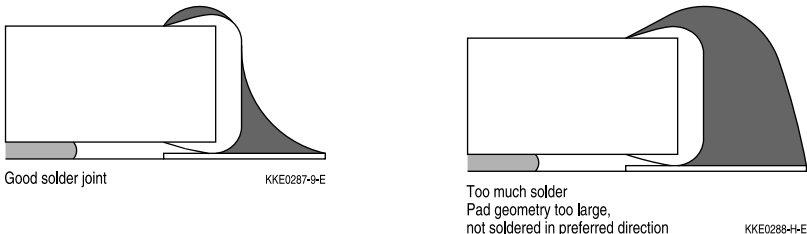
4.1 Nickel barrier termination

If the meniscus height is too low, that means the solder quantity is too low, the solder joint may break, i.e. the component becomes detached from the joint. This problem is sometimes interpreted as leaching of the external terminations.

If the solder meniscus is too high, i.e. the solder quantity is too large, the vise effect may occur. As the solder cools down, the solder contracts in the direction of the component. If there is too much solder on the component, it has no leeway to evade the stress and may break, as in a vise.

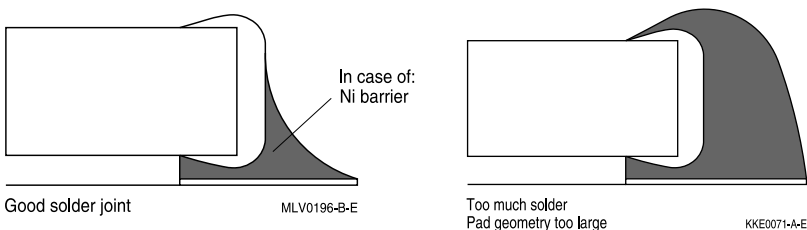
The figures below show good and poor solder joints for dual-wave and infrared soldering.

4.1.1 Solder joint profiles for nickel barrier termination - dual-wave soldering



Good and poor solder joints caused by amount of solder in dual-wave soldering.

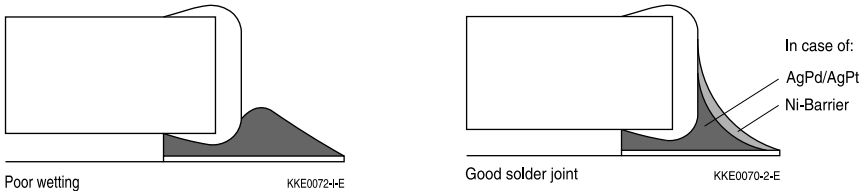
4.1.2 Solder joint profiles for nickel barrier termination / silver-palladium / silver-platinum termination - reflow soldering



Multilayer varistors (MLVs)

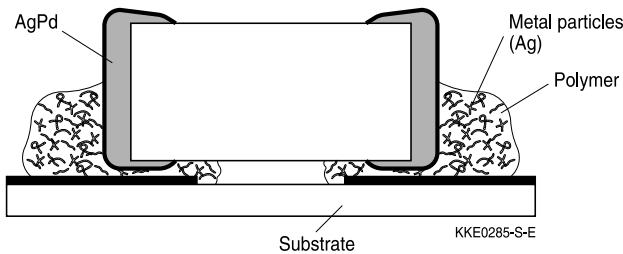
High-speed series

SMD



Good and poor solder joints caused by amount of solder in reflow soldering.

5 Conductive adhesion



Attaching surface-mounted devices (SMDs) with electrically conductive adhesives is a commercially attractive method of component connection to supplement or even replace conventional soldering methods.

Electrically conductive adhesives consist of a non-conductive plastic (epoxy resin, polyimide or silicon) in which electrically conductive metal particles (gold, silver, palladium, nickel, etc) are embedded. Electrical conduction is effected by contact between the metal particles.

Adhesion is particularly suitable for meeting the demands of hybrid technology. The adhesives can be deposited ready for production requirements by screen printing, stamping or by dispensers. As shown in the following table, conductive adhesion involves two work operations fewer than soldering.

Reflow soldering	Wave soldering	Conductive adhesion
Screen-print solder paste	Apply glue dot	Screen-print conductive adhesive
Mount SMD	Mount SMD	Mount SMD
Predry solder paste	Cure glue	Cure adhesive
Reflow soldering	Wave soldering	Inspect
Wash	Wash	
Inspect	Inspect	

**Multilayer varistors (MLVs)**
**High-speed series**
**SMD**

A further advantage of adhesion is that the components are subjected to virtually no temperature shock at all. The curing temperatures of the adhesives are between 120 °C and 180 °C, typical curing times are between 30 minutes and one hour.

The bending strength of glued chips is, in comparison with that of soldered chips, higher by a factor of at least 2, as is to be expected due to the elasticity of the glued joints.

The lower conductivity of conductive adhesive may lead to higher contact resistance and thus result in electrical data different to those of soldered components. Users must pay special attention to this in RF applications.

**6 Solderability tests**

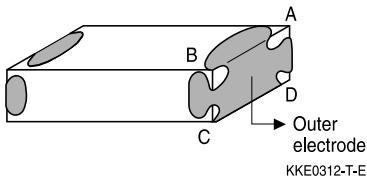
Test	Standard	Test conditions Sn-Pb soldering	Test conditions Pb-free soldering	Criteria/ test results
Wettability	IEC 60068-2-58	Immersion in 60/40 SnPb solder using non-activated flux at 215 ±3 °C for 3 ±0.3 s	Immersion in Sn96.5Ag3.0Cu0.5 solder using non- or low activated flux at 245 ±5 °C for 3 ±0.3 s	Covering of 95% of end termination, checked by visual inspection
Leaching resistance	IEC 60068-2-58	Immersion in 60/40 SnPb solder using mildly activated flux without preheating at 260 ±5 °C for 10 ±1 s	Immersion in Sn96.5Ag3.0Cu0.5 solder using non- or low activated flux without preheating at 255 ±5 °C for 10 ±1 s	No leaching of contacts
Thermal shock (solder shock)		Dip soldering at 300 °C/5 s	Dip soldering at 300 °C/5 s	No deterioration of electrical parameters. Capacitance change: DC/C <sub>0</sub> £ 15%
Tests of resistance to soldering heat for SMDs	IEC 60068-2-58	Immersion in 60/40 SnPb for 10 s at 260 °C	Immersion in Sn96.5Ag3.0Cu0.5 for 10 s at 260 °C	Change of varistor voltage: DV/V (1 mA) £ 5%
Tests of resistance to soldering heat for radial leaded components (SHCV)	IEC 60068-2-20	Immersion of leads in 60/40 SnPb for 10 s at 260 °C	Immersion of leads in Sn96.5Ag3.0Cu0.5 for 10 s at 260 °C	Change of varistor voltage: DV/V (1 mA) £ 5% Change of capacitance X7R: £ 5/+10%

**SMD**

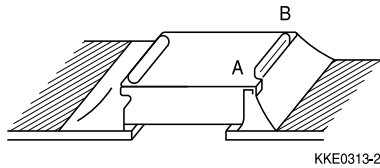
Note:

Leaching of the termination

Effective area at the termination might be lost if the soldering temperature and/or immersion time are not kept within the recommended conditions. Leaching of the outer electrode should not exceed 25% of the chip end area (full length of the edge A-B-C-D) and 25% of the length A-B, shown below as mounted on substrate.



As a single chip



As mounted on substrate

7 Notes for proper soldering

7.1 Preheating and cooling

■ According to JEDEC J-STD-020D. Please refer to chapter 2.

7.2 Repair / rework

Manual soldering with a soldering iron must be avoided, hot-air methods are recommended for rework purposes.

7.3 Cleaning

All environmentally compatible agents are suitable for cleaning. Select the appropriate cleaning solution according to the type of flux used. The temperature difference between the components and cleaning liquid must not be greater than 100 °C. Ultrasonic cleaning should be carried out with the utmost caution. Too high ultrasonic power can impair the adhesive strength of the metalized surfaces.

7.4 Solder paste printing (reflow soldering)

An excessive application of solder paste results in too high a solder fillet, thus making the chip more susceptible to mechanical and thermal stress. Too little solder paste reduces the adhesive strength on the outer electrodes and thus weakens the bonding to the PCB. The solder should be applied smoothly to the end surface.

## SMD

### 7.5 Adhesive application

Thin or insufficient adhesive causes chips to loosen or become disconnected during curing. Low viscosity of the adhesive causes chips to slip after mounting. It is advised to consult the manufacturer of the adhesive on proper usage and amounts of adhesive to use.

### 7.6 Selection of flux

Used flux should have less than or equal to 0.1 wt % of halogenated content, since flux residue after soldering could lead to corrosion of the termination and/or increased leakage current on the surface of the component. Strong acidic flux must not be used. The amount of flux applied should be carefully controlled, since an excess may generate flux gas, which in turn is detrimental to solderability.

### 7.7 Storage of CTVSs

Solderability is guaranteed for one year from date of delivery for multilayer varistors, CeraDiodes and ESD/EMI filters (half a year for chips with AgPd and AgPt terminations) and two years for SHCV and CU components, provided that components are stored in their original packages.

Storage temperature: 25 °C to +45 °C

Relative humidity: £75% annual average, £95% on 30 days a year

The solderability of the external electrodes may deteriorate if SMDs and leaded components are stored where they are exposed to high humidity, dust or harmful gas (hydrogen chloride, sulfurous acid gas or hydrogen sulfide).

Do not store SMDs and leaded components where they are exposed to heat or direct sunlight. Otherwise the packing material may be deformed or SMDs/ leaded components may stick together, causing problems during mounting.

After opening the factory seals, such as polyvinyl-sealed packages, it is recommended to use the SMDs or leaded components as soon as possible.

### 7.8 Placement of components on circuit board

Especially in the case of dual-wave soldering, it is of advantage to place the components on the board before soldering in that way that their two terminals do not enter the solder bath at different times.

Ideally, both terminals should be wetted simultaneously.

### 7.9 Soldering cautions

- An excessively long soldering time or high soldering temperature results in leaching of the outer electrodes, causing poor adhesion and a change of electrical properties of the varistor due to the loss of contact between electrodes and termination.
- Wave soldering must not be applied for MLVs designated for reflow soldering only.
- Keep the recommended down-cooling rate.

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7.10 Standards

CECC 00802

IEC 60068-2-58

IEC 60068-2-20

JEDEC J-STD-020D



**Multilayer varistors (MLVs)**
**High-speed series**
**SMD**
**Symbols and terms**

Symbol	Term
$C_{line,typ}$	Typical capacitance per line
$C_{max}$	Maximum capacitance
$C_{min}$	Minimum capacitance
$C_{nom}$	Nominal capacitance
$DC_{nom}$	Tolerance of nominal capacitance
$C_{typ}$	Typical capacitance
$f_{cut-off,min}$	Minimum cut-off frequency
$I$	Current
$I_{clamp}$	Clamping current
$I_{leak}$	Leakage current
$I_{leak,typ}$	Typical leakage current
$I_{PP}$	Peak pulse current
$I_{surge,max}$	Maximum surge current (also termed peak current)
LCT	Lower category temperature
$L_{typ}$	Typical inductance
$P_{diss,max}$	Maximum power dissipation
$P_{PP}$	Peak pulse power
$R_{ins}$	Insulation resistance
$R_{min}$	Minimum resistance
$R_S$	Resistance per line
$T_A$	Ambient temperature
$T_{op}$	Operating temperature
$T_{stg}$	Storage temperature
$t_r$	Duration of equivalent rectangular wave
$t_{resp}$	Response time
UCT	Upper category temperature
$V$	Voltage
$V_{BR,min}$	Minimum breakdown voltage
$V_{clamp,max}$	Maximum clamping voltage
$V_{DC,max}$	Maximum DC operating voltage (also termed working voltage)
$V_{ESD,air}$	Air discharge ESD capability
$V_{ESD,contact}$	Contact discharge ESD capability
$V_{jump}$	Maximum jump-start voltage

Multilayer varistors (MLVs)

High-speed series

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$V_{RMS,max}$	Maximum AC operating voltage, root-mean-square value
$V_V$	Varistor voltage (also termed breakdown voltage)
$V_{V,min}$	Minimum varistor voltage
$V_{V,max}$	Maximum varistor voltage
$DV_V$	Tolerance of varistor voltage
$W_{LD}$	Maximum load dump
$W_{max}$	Maximum energy absorption (also termed transient energy)
$a_{typ}$	Typical insertion loss
$e$	Lead spacing
*	Maximum possible application conditions

All dimensions are given in mm.

The commas used in numerical values denote decimal points.

SMD

Cautions and warnings

General

Some parts of this publication contain statements about the suitability of our ceramic transient voltage suppressor (CTVS) components (multilayer varistors (MLVs), CeraDiodes, ESD/EMI filters, SMD disk varistors (CU types), leaded transient voltage/ RFI suppressors (SHCV types)) for certain areas of application, including recommendations about incorporation/design-in of these products into customer applications. The statements are based on our knowledge of typical requirements often made of our CTVS devices in the particular areas. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our CTVS components for a particular customer application. As a rule, EPCOS is either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always incumbent on the customer to check and decide whether the CTVS devices with the properties described in the product specification are suitable for use in a particular customer application.

- Do not use EPCOS CTVS components for purposes not identified in our specifications, application notes and data books.
- Ensure the suitability of a CTVS in particular by testing it for reliability during design-in. Always evaluate a CTVS component under worst-case conditions.
- Pay special attention to the reliability of CTVS devices intended for use in safety-critical applications (e.g. medical equipment, automotive, spacecraft, nuclear power plant).

Design notes

- Always connect a CTVS in parallel with the electronic circuit to be protected.
- Consider maximum rated power dissipation if a CTVS has insufficient time to cool down between a number of pulses occurring within a specified isolated time period. Ensure that electrical characteristics do not degrade.
- Consider derating at higher operating temperatures. Choose the highest voltage class compatible with derating at higher temperatures.
- Surge currents beyond specified values will puncture a CTVS. In extreme cases a CTVS will burst.
- If steep surge current edges are to be expected, make sure your design is as low-inductance as possible.
- In some cases the malfunctioning of passive electronic components or failure before the end of their service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In applications requiring a very high level of operational safety and especially when the malfunction or failure of a passive electronic component could endanger human life or health (e.g. in accident prevention, life-saving systems, or automotive battery line applications such as clamp 30), ensure by suitable design of the application or other measures (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of such a malfunction or failure. Only use CTVS components from the automotive series in safety-relevant applications.

### SMD

- Specified values only apply to CTVS components that have not been subject to prior electrical, mechanical or thermal damage. The use of CTVS devices in line-to-ground applications is therefore not advisable, and it is only allowed together with safety countermeasures like thermal fuses.

#### Storage

- Only store CTVS in their original packaging. Do not open the package before storage.
- Storage conditions in original packaging: temperature 25 to +45°C, relative humidity £75% annual average, maximum 95%, dew precipitation is inadmissible.
- Do not store CTVS devices where they are exposed to heat or direct sunlight. Otherwise the packaging material may be deformed or CTVS may stick together, causing problems during mounting.
- Avoid contamination of the CTVS surface during storage, handling and processing.
- Avoid storing CTVS devices in harmful environments where they are exposed to corrosive gases for example (SO<sub>x</sub>, Cl).
- Use CTVS as soon as possible after opening factory seals such as polyvinyl-sealed packages.
- Solder CTVS components after shipment from EPCOS within the time specified:
  - CTVS with Ni barrier termination, 12 months
  - CTVS with AgPd and AgPt termination, 6 months
  - SHCV and CU series, 24 months

#### Handling

- Do not drop CTVS components and allow them to be chipped.
- Do not touch CTVS with your bare hands - gloves are recommended.
- Avoid contamination of the CTVS surface during handling.
- Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.

#### Mounting

- When CTVS devices are encapsulated with sealing material or overmolded with plastic material, electrical characteristics might be degraded and the life time reduced.
- Make sure an electrode is not scratched before, during or after the mounting process.
- Make sure contacts and housings used for assembly with CTVS components are clean before mounting.
- The surface temperature of an operating CTVS can be higher. Ensure that adjacent components are placed at a sufficient distance from a CTVS to allow proper cooling.
- Avoid contamination of the CTVS surface during processing.
- Multilayer varistors (MLVs) with AgPd termination are not approved for lead-free soldering.

## Multilayer varistors (MLVs)

### High-speed series

#### SMD

#### Soldering

- Complete removal of flux is recommended to avoid surface contamination that can result in an instable and/or high leakage current.
- Use resin-type or non-activated flux.
- Bear in mind that insufficient preheating may cause ceramic cracks.
- Rapid cooling by dipping in solvent is not recommended, otherwise a component may crack.

#### Conductive adhesive gluing

- Only multilayer varistors (MLVs) with an AgPd termination are approved for conductive adhesive gluing.

#### Operation

- Use CTVS only within the specified operating temperature range.
- Use CTVS only within specified voltage and current ranges.
- Environmental conditions must not harm a CTVS. Only use them in normal atmospheric conditions. Reducing the atmosphere (e.g. hydrogen or nitrogen atmosphere) is prohibited.
- Prevent a CTVS from contacting liquids and solvents. Make sure that no water enters a CTVS (e.g. through plug terminals).
- Avoid dewing and condensation.
- EPCOS CTVS components are mainly designed for encased applications. Under all circumstances avoid exposure to:
  - direct sunlight
  - rain or condensation
  - steam, saline spray
  - corrosive gases
  - atmosphere with reduced oxygen content
- EPCOS CTVS devices are not suitable for switching applications or voltage stabilization where static power dissipation is required.
- Multilayer varistors (MLVs) are designed for ESD protection and transient suppression. CeraDiodes are designed for ESD protection only, ESD/EMI filters are designed for ESD and EMI protection only.

This listing does not claim to be complete, but merely reflects the experience of EPCOS AG.

The following applies to all products named in this publication:

1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule, EPCOS is either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an EPCOS product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or lifesaving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. The warnings, cautions and product-specific notes must be observed.
4. In order to satisfy certain technical requirements, some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous). Useful information on this will be found in our Material Data Sheets on the Internet ([www.epcos.com/material](http://www.epcos.com/material)). Should you have any more detailed questions, please contact our sales offices.
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